

Electronic Patent Application Fee Transmittal

Application Number:	10524525
Filing Date:	18-Aug-2005
Title of Invention:	Method for selectively removing material from the surface of a substrate, masking material for a wafer, and wafer with masking material
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Filer:	David H. Brinkman/Rhonda Etienne
Attorney Docket Number:	BEET-09

Filed as Large Entity

U.S. National Stage under 35 USC 371 Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Submission- Information Disclosure Stmt	1806	1	180	180
Total in USD (\$)				180